

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Masaru ICHIKAWA	04/06/2011
Yoshinori TANIMOTO	04/06/2011
Tsuneo AKIURA	04/06/2011
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13095522
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CH \$40.00 13095522

ATTORNEY DOCKET NUMBER:	0229-1145PUS1
NAME OF SUBMITTER:	Andrew D. Meikle
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif	

BIRCH, STEWART, KOLASCH & BIRCH, LLP

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

ASSIGNMENT

Application No. 13/095,522

Filed April 27, 2011

**Insert Name(s)
of Inventor(s)**

***** (Given Name FAMILY NAME (ALL CAPS)) *****

WHEREAS, Masaru ICHIKAWA, Yoshinori TANIMOTO and
Tsuneo AKIURA

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in

**Insert Title
of Invention**

Wire catalyst for hydrogenation/dehydrogenation reaction and
Manufacturing method therefor

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application).

**Insert Date
of Signing of
Application**

on April 6, 2011 ; and

**Insert Name
of Assignee**

WHEREAS, (1) NIPPON SEISEN CO., LTD. and (2) Masaru ICHIKAWA

**Insert Address
of Assignee**

of (1) 1-1, Kouraibashi 4-chome, Chuo-ku, Osaka 541-0043 Japan
(2) 25-17, Honamanuma 2-chome, Suginami-ku, Tokyo 167-0031 Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

**CHECK BOX
IF APPROPRIATE**

in any foreign countries.

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date <u>6 April, 2011</u> ,	Name of Inventor <u>Masaru Ichikawa</u> (signature) Masaru ICHIKAWA
Date <u>8 April 2011</u> ,	Name of Inventor <u>Yoshinori Tanimoto</u> (signature) Yoshinori TANIMOTO
Date <u>6 April 2011</u> ,	Name of Inventor <u>Tsuneo Akiura</u> (signature) Tsuneo AKIURA
Date _____ ,	Name of Inventor _____ (signature)
Date _____ ,	Name of Inventor _____ (signature)
Date _____ ,	Name of Inventor _____ (signature)